Attorney Docket No. 5649-905

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

é: Hong-Sik Jeong et al. erial No.: 10/008,700

Confirmation No.: 5150 Group Art Unit: 2818

Filed: December 7, 2001

Examiner: Chuong A. Luu METHODS OF MANUFACTURING INTEGRATED CIRCUIT DEVICES

HAVING AN ENCAPSULATED INSULATION LAYER

Date: April 18, 2006

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

AMENDMENT

Sir:

For:

Applicants provide the present Amendment to address the issues raised in the Official Action mailed October 18, 2005.

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 6 of this paper.

It is not believed that an extension of time and/or additional fee(s), including fees for net addition of claims, are required, beyond those that may otherwise be provided for in documents accompanying this paper. In the event, however, that an extension of time is necessary to allow consideration of this paper, such an extension is hereby petitioned under 37 C.F.R. §1.136(a). Any additional fees believed to be due in connection with this paper may be charged to our Deposit Account No. 50-0220.